

RoHS

目錄
MAPX设变内容
MODIFICATION日期
DATE

NOTE:

1.MATERIAL SPECIFICATION:

- 1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.
- 2.CONTACTS:COPPER ALLOY
- 3.MID PLATE: STAINLESS STEEL
- 4.FRONT SHELL: STAINLESS STEEL

2.PLATING SPECIFICATION:

2-1.CONTACTS:

- Ni 50u" MIN. UNDER PLATED OVER ALL.
Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
(GOLD PLATING THICKNESS FOLLOW THE P/N)
PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N

2-2.FRONT SHELL:

SEE TABLE1.

2-3.SHIELD PLATE&EMI PLATE:

CLEAR ONLY

3.MECHANICAL PERFORMANCE,

- 3-1.INSERTION FORCE: 0.5~2.0kgf.
- 3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
- 3-3.DURABILITY: 5000 CYCLES.

4.ELECTRICAL PERFORMANCE,

- 4-1. CURRENT RATING:3.0A
VOLTAGE RATING:5.0V
- 4-2. LLCR:
VBUS & GND PINS AND OTHER PINS: 40m?/PIN MAX.
SHIELD: 50m?/MAX.
LLCR MAX. CHANGE OF ALL PINS: 10m?.
- 4-3.INSULATION RESISTANCE: 100M? MIN
- 4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.

5. ENVIRONMENTAL PERFORMANCE:

OPERATING TEMPERATURE: -25°C~+85°C.

6.IR REFLOW:

THE PEAK TEMPERATURE ON THE BOARD SHALL
BE MAINTAINED FOR 10 SECONDS AT 260°C.

PIN ASSIGNMENTS

A5	CC1	B12	GND
A9	VBUS	B9	VBUS
A12	GND	B5	CC2
PIN	SIGNAL NAME	PIN	SIGNAL NAME

产品图

PRODUCT CHART DWG

公差一览表

TOLERANCE UNLESS OTHERWISE

X.	±0.35	X'.	±5°
.X	±0.30	.X"	±2°
.XX	±0.25	.XX"	±1°
.XXX	±0.10	.XXX"	±0.5°



深圳市精拓金电子有限公司
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单位
UNITS

MM

制图
DRAWING

Erick

产品料号
PRODUCT PART NO.

918-418K2028S40006

比例
SCALE

1:1

审核
CHKD

L S S

产品名称
PRODUCT NO.TYPE-C3.1母座板上6.8四脚
全贴无弹单排SMT6PIN日期
DATE

2021/03/10

核准
APPD

黄国荣

角法
VIEW版本
VER

A0